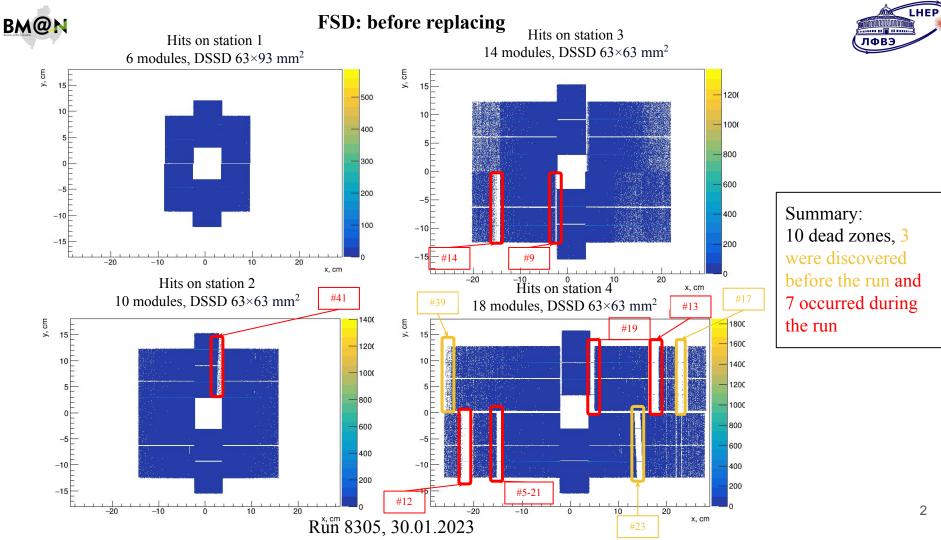




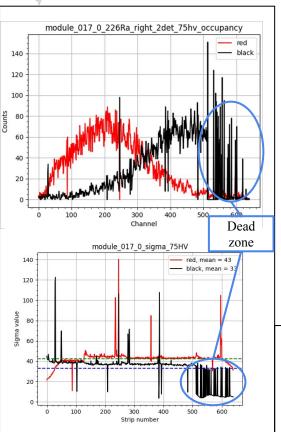
# Forward Silicon Tracker status

Danil Chemezov on behalf of Forward Silicon Tracker team

Analysis and Detector Meeting of the BM@N Experiment, 12-13 March 2024







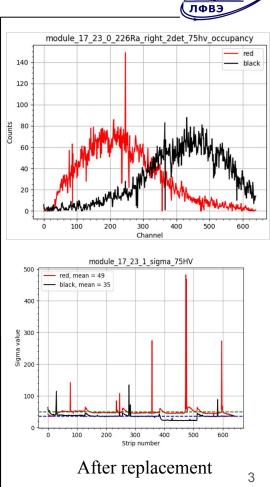
Before replacement

# FEE board replacing

### Replacement process



To eliminate the dead zones it was necessary to assemble a new FEE board completely, 5 ASICs were spent to eliminate each of defects. The old boards were disconnected from the modules and replaced with a new ones. Total: 9 new black boards (p+ strips) were built, 45 VATAGP 7.2 ASICs were used (30 spare ASICs available).





## **Repairable FEE boards with new compound**



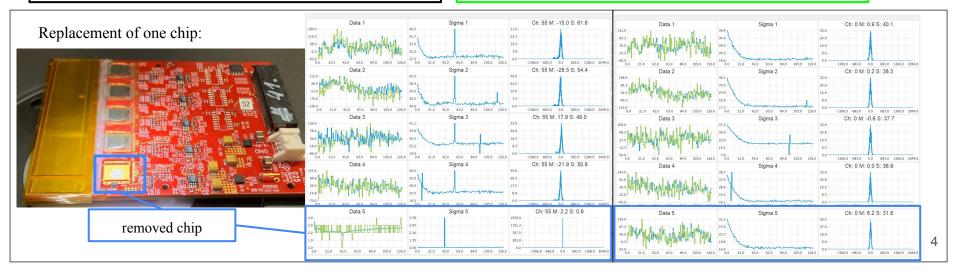


Black BE-08 encapsulant (polarization temperature 100°C) Ultra Light-

- an additional optical shield for chips
- Not removable mechanically or with chemical solvents (dimethyl sulfoxide, dimethylformamide, CH<sub>2</sub>O<sub>2</sub>)

Ultra Light-Weld 9008 Flexible, UV-Curable Encapsulant

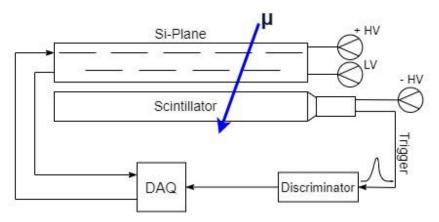
- Does not create an additional optical shield
- Can be mechanically removed so **FEE boards are** repairable





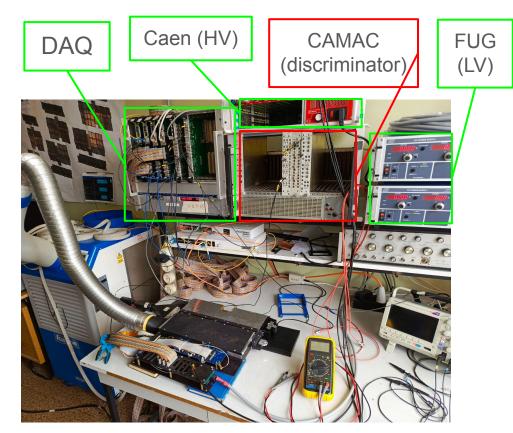
### **Cosmic tests of FSD**





Dimensions:

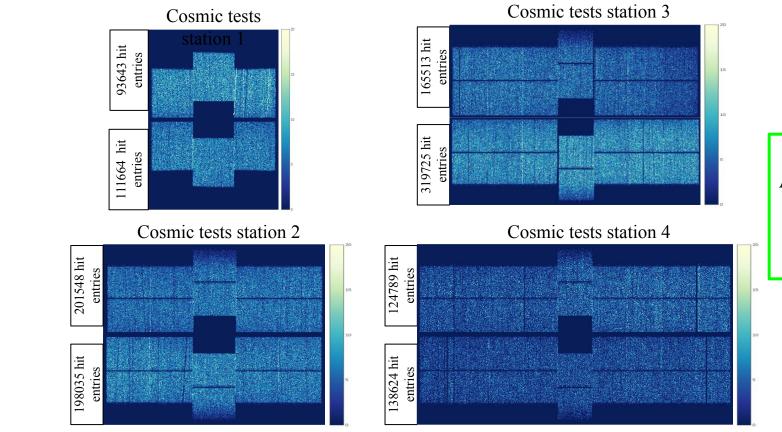
- Scintillator: 150x600 mm<sup>2</sup>
- Station 1 half-plane: 93x180 mm<sup>2</sup>
- Station 2 half-plane: 126x300 mm<sup>2</sup>
- Station 3 half-plane: 126x420 mm<sup>2</sup>
- Station 4 half-plane: 126x540mm<sup>2</sup>





# FSD: after replacing





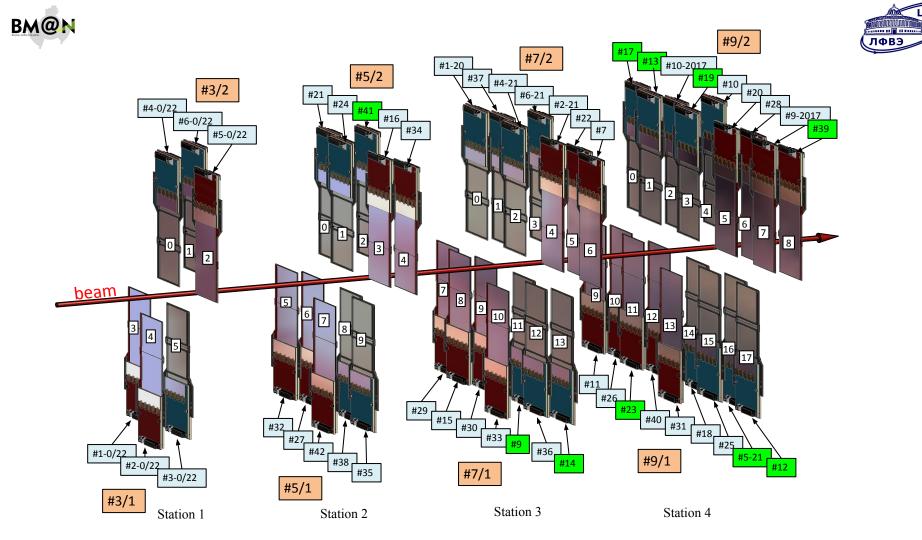
All dead zones have been eliminated!



# Conclusion



- We get information about problematic modules from Xe-run results;
- Based on test results, we localize the defect: № module, PCB-type (p+ or n+), №chip on PCB;
- For transparent encapsulant: we can replace a single chip without damaging the others;
- For black encapsulant: replace the entire board, because BE-08 encapsulant not removable;
- 30 spare chips available;
- We are testing removed PCBs and trying to determine cause and type of defects for problematic chips



LHEP

